

Title (en)
SOLDER PREFORM FOR DIFFUSION SOLDERING, METHOD FOR THE PRODUCTION THEREOF AND METHOD FOR THE ASSEMBLY THEREOF

Title (de)
LOTFORMTEIL ZUM DIFFUSIONSLÖTEN, VERFAHREN ZU DESSEN HERSTELLUNG UND VERFAHREN ZU DESSEN MONTAGE

Title (fr)
PIÈCE MOULÉE DE SOUDURE POUR LE SOUDAGE PAR DIFFUSION, SON PROCÉDÉ DE FABRICATION ET SON PROCÉDÉ DE MONTAGE

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Application
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Abstract (en)
[origin: WO2018197314A1] The invention relates to a solder preform (11) for diffusion soldering. This consists of metal films (12), between which a paste (16) containing particles (15) is retained. The particles can consist of a soldering material, for example, while the films (12) consist of copper, for example. With the forming of the solder connection, intermetallic connections of the diffusion solder connection occur in a diffusion zone. The advantage of the use of a paste for producing the sandwich structure in the solder preform (11) lies in the fact that production is simplified and the paste (16) can guarantee a tolerance compensation to a certain extent. As well as the solder preform (11), the invention also relates to a method for producing a solder preform of this type, and a method for forming a diffusion solder connection with this solder preform.

IPC 8 full level
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